Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Previously presented) A surface-mountable radiation-emitting component, comprising:

a leadframe and a radiation-emitting chip mounted on said leadframe;

a molding material encasing said leadframe and said radiation-emitting chip, the molding material having a shape defining a mounting surface of the component, said mounting surface extending at a first predetermined angle, said first predetermined angle having a value lying within a range from 0° to 20° relative to a main emission direction of the component, said molding material having a shape defining a curved surface in the main emission direction; and

said leadframe having leadframe connections, wherein said leadframe connections protrude out of said molding material and have connection surfaces which enclose a second predetermined angle with said mounting surface, said second predetermined angle having a value lying within a range from 70° to 90°.

2. (Original) The component according to claim 1, wherein said leadframe connections, viewed from said mounting surface, are led laterally out of said molding material.

3. (Canceled).

4. (Currently amended) The component according to claim 1, wherein said second predetermined angle has a value of substantially 90° ~~or lies within a from 70° to 90°~~.

5-6. (Canceled)

7. (Original) The component according to claim 1, wherein said leadframe connections extend up to a mounting plane defined by said mounting surface.

8. (Original) The component according to claim 1, wherein said leadframe connections extend into a vicinity of a mounting plane defined by said mounting surface.

9. (Original) The component according to claim 1, wherein said leadframe is substantially flat.

10. (Original) The component according to claim 1, wherein said leadframe is formed with voids selected from the group consisting of passages and lateral recesses within a region surrounded by said molding material.

11. (Original) The component according to claim 1, wherein said molding material has a top surface parallel to said mounting surface.

12. (Original) The component according to claim 1, wherein said molding material, viewed from said radiation-emitting chip, is formed with a curved surface in a main emission direction.

13. (Original) The component according to claim 11, wherein said curved surface is selected from the group consisting of a part-cylindrical surface, part-spherical surface and part-aspherical surface.

14. (Original) The component according to claim 1, wherein said radiation-emitting chip contains a compound selected from the group consisting of GaN, InGaN, AlGaN, InAlGaN, ZnS, ZnSe, CdZnS and CdZnSe.

15. (Original) The component according to claim 1, wherein said radiation-emitting chip is configured to emit radiation selected from the group consisting of visible light, infrared radiation, and ultraviolet electromagnetic radiation.

16. (Original) The component according to claim 1, wherein said molding material is a radiation-permeable plastics compression molding material.

17. (Original) The component according to claim 1, wherein said molding material is a resin-based material.

18. (Original) The component according to claim 1, which comprises conversion material distributed in said molding material.

19. (Original) The component according to claim 1, wherein said molding material consists essentially of a prereacted epoxy resin.

20. (Original) The component according to claim 19, wherein said epoxy resin is epoxy novolak or epoxy-cresol novolak.

21. (Original) The component according to claim 19, wherein said epoxy resin has been prereacted with at least one of a phenol curing agent and an anhydride curing agent.

22. (Original) The component according to claim 19, wherein said conversion material contains a material selected from the group consisting of an organic phosphor, an inorganic phosphor, and a mixture thereof.

23. (Original) The component according to claim 22, wherein said phosphor contains a phosphor metal center M in a host lattice based on the general formula $A_3B_5X_{12}$.

24. (Original) The component according to claim 22, wherein said phosphor contains a phosphor metal center M in a host lattice based on a sulfide, oxysulfide, borate, aluminate, or metal chelate complex.

25. (Original) The component according to claim 23, wherein said phosphor is selected from the group consisting of YAG:Ce, TAG:Ce, TbYAG:Ce, GdYAG:Ce, GdTbYAG:Ce, and mixtures thereof.

26. (Original) The component according to claim 1, wherein said molding material contains an adhesion promoter.

27. (Original) The component according to claim 26, wherein said adhesion promoter is 3–glycidyloxypropyltrimethoxysilane or further derivatives based on trialkoxysilane.

28. (Original) The component according to claim 18, wherein said molding material contains a surface modifier for modifying a surface of said conversion material.

29. (Original) The component according to claim 28, wherein said surface modifier is diethylene glycol monomethyl ether.

30. (Original) The component according to claim 1, wherein said molding material contains a mold release agent or a lubricant.

31. (Original) The component according to claim 30, wherein said mold release agent is a wax-based mold release agent or a metal soap with long-chain carboxylic acids.

32. (Original) The component according to claim 30, wherein said mold release agent is a stearate.

33. (Original) The component according to claim 1, wherein said molding material contains inorganic fillers for increasing a refractive index of said molding material.

34. (Original) The component according to claim 33, wherein said inorganic fillers are selected from the group consisting of TiO_2, ZrO_2, α–Al_2O_3, and other metal oxides.

35. (Original) The component according to claim 1, wherein said molding material contains glass particles.

36. (Original) The component according to claim 35, wherein said glass particles have a mean particle size of less than 100 μm.

37. (Original) The component according to claim 35, wherein said glass particles have a mean particle size of less than 50 μm.

38. (Original) The component according to claim 35, wherein a proportion of said glass particles in said molding material is between 0% by weight and 90% by weight.

39. (Original) The component according to claim 35, wherein a proportion of said glass particles in said molding material is between 10% by weight and 50% by weight.

40. (Original) The component according to claim 1, wherein said molding material is a mixture containing the following constituents:

plastics compression molding material ≥ 60%;

conversion material ≥ 0% and ≤ 40%;

adhesion promoter ≥ 0% and ≤ 3%;

mold release agent ≥ 0% and ≤ 2%;

surface modifier ≥ 0% and ≤ 5%;

antioxidant ≥ 0% and ≤ 5%;

UV light stabilizer ≥ 0% and ≤ 2%; and

glass particles ≥ 0% and ≤ 90%.

41. (Original) The component according to claim 40, wherein said conversion material is present in an amount of > 10% and ≤ 25% and said antioxidant is based on phosphite or on sterically hindered phenols.

42. (Original) The component according to claim 18 configured to produce radiation selected from the group consisting of mixed-color light, white light, infrared, and ultraviolet electromagnetic radiation.

43. (Original) A method of producing the component according to claim 1, which comprises the following steps:

preparing a molding material from a resin powder prereacted with curing agent, and optionally further fillers; and

encasing the leadframe and the radiation-emitting chip mounted thereon with the molding material to form the component according to claim 1.

44-86. (Canceled)

87. (Previously presented) The component according to claim 1 wherein the shape of the molding material further defines side surfaces that are substantially perpendicular to the mounting surface, and wherein the leadframe connections protrude out of the side surfaces.